

Characteristics

Table 1. Absolute ratings (limiting values at 25 °C, unless otherwise specified)

Symbol	Param	neter	Value	Unit	
V _{RRM}	Repetitive peak reverse voltage (T _j = -40 °C to	o +175 °C)	1200	V	
I _{F(RMS)}	Forward rms current		38	Α	
I _{F(AV)}	Average forward current	T _c = 155 °C, DC current	20	Α	
I _{FRM}	Repetitive peak forward current	$T_c = 155 ^{\circ}\text{C}, T_j = 175 ^{\circ}\text{C}, \delta = 0.1$	78	Α	
		t _p = 10 ms sinusoidal, T _c = 25 °C	140		
I _{FSM}	Surge non repetitive forward current	t _p = 10 ms sinusoidal, T _c = 150 °C	120	Α	
		t _p = 10 μs square, T _c = 25 °C	700		
T _{stg}	Storage temperature range		-55 to +175	°C	
Tj	Operating junction temperature ⁽¹⁾	-40 to +175	°C		

^{1.} $(dP_{tot}/dT_j) < (1/R_{th(j-a)})$ condition to avoid thermal runaway for a diode on its own heatsink.

Table 2. Thermal resistance parameters

Symbol	Parameter	Va	Unit	
Зушьог	r ai ailletei	Тур.	Max.	Onit
R _{th(j-c)}	Junction to case	0.30	0.45	°C/W

Table 3. Static electrical characteristics

	Symbol	Parameter	Test conditions		Min.	Тур.	Max.	Unit
ſ	. (1)	L (1)		\\- = \\ \	-	10	120	
	IR (1)	I _R ⁽¹⁾ Reverse leakage current	T _j = 150 °C	$V_R = V_{RRM}$	-	60	800	μA
	V (2)	Convert voltage dren	T _j = 25 °C	I _E = 20 A	-	1.35	1.50	V
	VF (=)	$V_F^{(2)}$ Forward voltage drop $T_j = 150 ^{\circ}\text{C}$ $I_F = 20 ^{\circ}\text{A}$	-	1.75	2.25	V		

^{1.} Pulse test: t_p = 5 ms, δ < 2%

To evaluate the conduction losses, use the following equation: $P = 1.07 \times I_{F(AV)} + 0.059 \times I_{F^2(RMS)}$

Table 4. Dynamic electrical characteristics

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
Q _{Cj} (1)	Total capacitive charge	V _R = 800 V	-	129	-	nC
Ci	Total capacitance	$V_R = 0 \text{ V}, T_c = 25 \text{ °C}, F = 1 \text{ MHz}$	-	1650	-	pF
	Total capacitance	$V_R = 800 \text{ V}, T_c = 25 \text{ °C}, F = 1 \text{ MHz}$	-	110	-	ρı

Most accurate value for the capacitive charge: $Q_{cj}(V_R) = \int\limits_0^{V_R} C_j(V) dV$

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^{2.} Pulse test: $t_p = 500 \ \mu s, \ \delta < 2\%$



1.1 Characteristics (curves)

Figure 1. Forward voltage drop versus forward current (typical values)

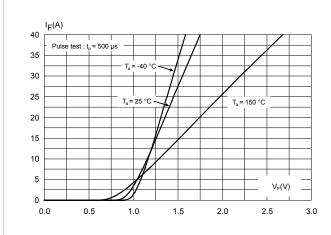


Figure 2. Reverse leakage current versus reverse voltage applied (typical values)

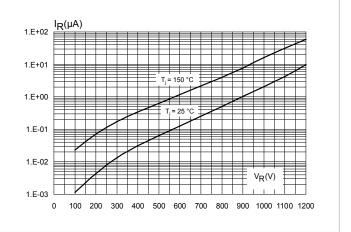


Figure 3. Peak forward current versus case temperature

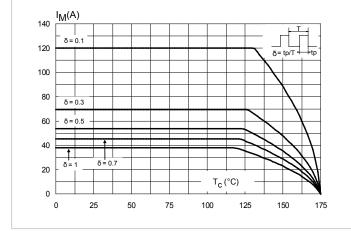
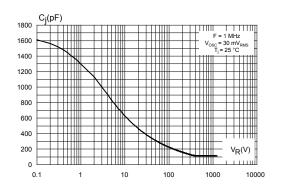


Figure 4. Junction capacitance versus reverse voltage applied (typical values)



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Figure 5. Relative variation of thermal impedance junction to case versus pulse duration

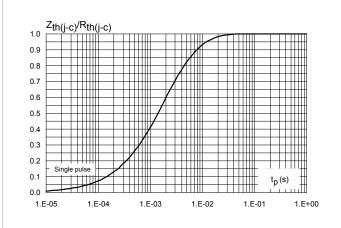


Figure 6. Non-repetitive peak surge forward current versus pulse duration (sinusoidal waveform)

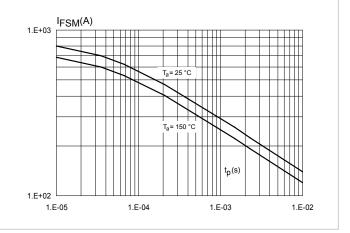


Figure 7. Total capacitive charges versus reverse voltage applied (typical values)

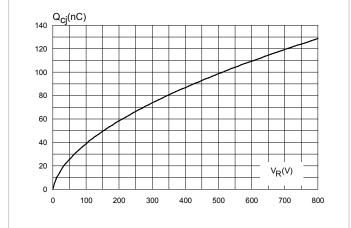
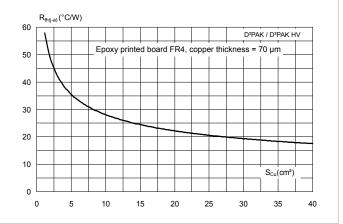


Figure 8. Thermal resistance junction to ambient versus copper surface under tab (typical values, epoxy printed board FR4, e_{Cu} = 70 μm)



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Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

2.1 TO-220AC package information

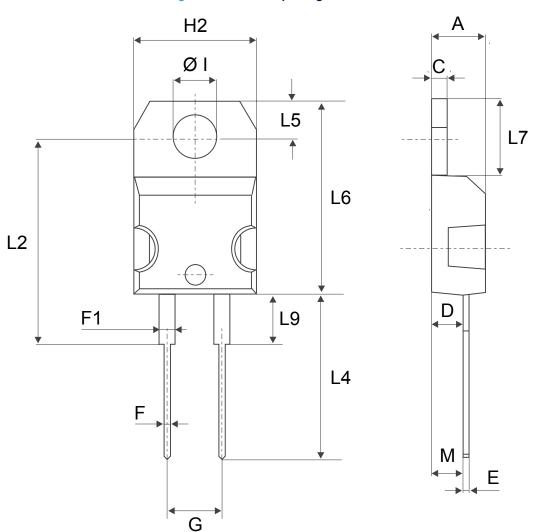
• Epoxy meets UL 94,V0

Cooling method: by conduction (C)

Recommended torque value: 0.55 N·m

Maximum torque value: 0.70 N·m

Figure 9. TO-220AC package outline



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Table 5. TO-220AC package mechanical data

		Dimer	nsions		
Ref.	Millim	neters	Incl	nes	
	Min.	Max.	Min.	Max.	
Α	4.40	4.60	0.173	0.181	
С	1.23	1.32	0.048	0.051	
D	2.40	2.72	0.094	0.107	
E	0.49	0.70	0.019	0.027	
F	0.61	0.88	0.024	0.034	
F1	1.14	1.70	0.044	0.066	
G	4.95	5.15	0.194	0.202	
H2	10.00	10.40	0.393	0.409	
L2	16.40	typ.	0.645 typ.		
L4	13.00	14.00	0.511	0.551	
L5	2.65	2.95	0.104	0.116	
L6	15.25	15.75	0.600	0.620	
L7	6.20	6.60	0.244	0.259	
L9	3.50	3.93	0.137	0.154	
M	2.6	typ.	0.102	typ.	
ØI	3.75	3.85	0.147	0.151	



2.2 D²PAK package information

- Epoxy meets UL94, V0.
- Cooling method: by conduction (C)

Figure 10. D²PAK package outline

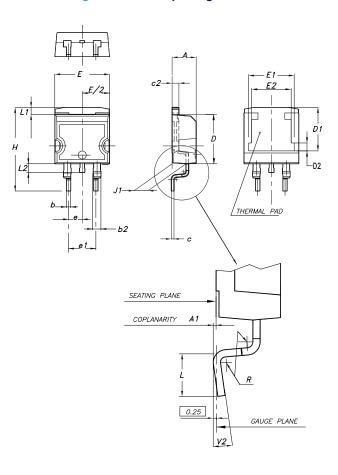


Table 6. D²PAK package mechanical data

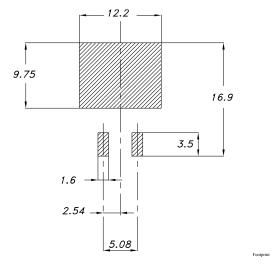
			Dimer	nsions		
Ref.		Millimeters			Inches	
	Min.	Тур.	Max.	Min.	Тур.	Max.
Α	4.40		4.60	0.173		0.181
A1	0.03		0.23	0.001		0.009
b	0.70		0.93	0.028		0.037
b2	1.14		1.70	0.045		0.067
С	0.45		0.60	0.018		0.024
c2	1.23		1.36	0.048		0.053
D	8.95		9.35	0.352		0.368
D1	7.50	7.75	8.00	0.295	0.305	0.315
D2	1.10	1.30	1.50	0.043	0.051	0.060
Е	10		10.40	0.394		0.409

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			Dime	nsions		
Ref.		Millimeters			Inches	
	Min.	Тур.	Max.	Min.	Тур.	Max.
E1	8.30	8.50	8.70	0.326	0.335	0.343
E2	6.85	7.05	7.25	0.266	0.278	0.282
е		2.54			0.100	
e1	4.88		5.28	0.190		0.205
Н	15		15.85	0.591		0.624
J1	2.49		2.69	0.097		0.106
L	2.29		2.79	0.090		0.110
L1	1.27		1.40	0.049		0.055
L2	1.30		1.75	0.050		0.069
R		0.4			0.015	
V2	0°		8°	0°		8°

Figure 11. D²PAK recommended footprint (dimensions are in mm)

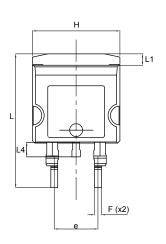


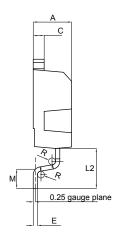
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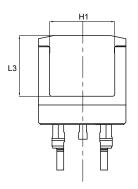


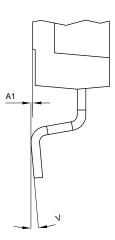
2.3 D²PAK high voltage package information

Figure 12. D²PAK high voltage package outline









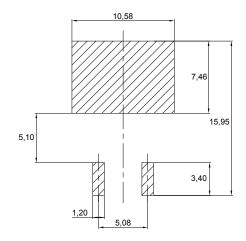
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Table 7. D²PAK high voltage package mechanical data

Def.	Dimensions					
Ref.	Min.	Тур.	Max.			
А	4.30		4.70			
A1	0.03		0.20			
С	1.17		1.37			
е	4.98		5.18			
E	0.50		0.90			
F	0.78		0.85			
Н	10.00		10.40			
H1	7.40		7.80			
L	15.30		15.80			
L1	1.27		1.40			
L2	4.93		5.23			
L3	6.85		7.25			
L4	1.5		1.7			
M	2.6		2.9			
R	0.20		0.60			
V	0°		8°			

Figure 13. D²PAK High Voltage footprint in mm



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2.3.1 Creepage distance between Anode and Cathode

Table 8. Creepage distance between anode and cathode

Symbol	Parameter		Value	Unit
Cd _{A-K1}	Minimum creepage distance between A and K1 (with top coating)		5.38	
Cd _{A-K2}	Minimum creepage distance between A and K2 (without top coating)		3.48	mm

Note: D²PAK HV creepage distance (anode to cathode) = 5.38 mm min. (refer to IEC 60664-1)

Figure 14. Creepage with top coating

Creepage A

Minimum distance between A & K1 = 5.38 mm (with top coating)

Figure 15. Creepage without top coating

Creepage

Minimum distance between A & K2 = 3.48 mm (without top coating)

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3 Ordering information

Table 9. Ordering information

Order code	Marking	Package	Weight	Base qty.	Delivery mode
STPSC20H12DY	STPSC20H12DY	TO-220AC	1.86 g	50	Tube
STPSC20H12GY-TR	STPSC20H12GY	D²PAK	1.48 g	1000	Tape and reel
STPSC20H12G2Y-TR	SC20H12G2Y	D²PAK HV	1.48 g	1000	Tape and reel



Revision history

Table 10. Document revision history

Date	Revision	Changes
05-Jan-2017	1	Initial release.
23-Jan-2017	2	Added D²PAK package.
18-Dec-2017	3	Updated cover image.
02-May-2019	4	Added D²PAK HV package.

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